Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

(Currently Amended) An electronic component comprising:

 a substrate having a through hole formed in a thickness direction thereof; and
 a conductor, disposed in the through hole, for electrically connecting one side

 of the substrate to the other side thereof;

wherein the through hole has a major axis diameter and a minor axis diameter on at least one of one side and the other side of the substrate;

wherein the through hole comprises a plurality of holes arranged along the thickness direction of the substrate;

wherein the holes formed adjacent each other in the thickness direction of the
substrate have respective center axes shifted from each other as seen in a predetermined
direction orthogonal to the thickness direction of the substrate; and

wherein the predetermined direction orthogonal to the thickness direction of the substrate is the minor axis direction of the through hole.

2. (Currently Amended) AnThe electronic component according to claim 1, wherein the through hole has a form satisfying

$$1 < (D3/D4) \le 5$$

where D3 is the major axis diameter on the one side, and D4 is the minor axis diameter on the one side.

3. (Currently Amended) AnThe electronic component according to claim 1, wherein the through hole has a form satisfying

$$0.4 \le (D5/D4) \le 0.94$$

where D4 is the minor axis diameter on the one side, and D5 is the minor axis diameter on the other side.

- 4. (Canceled)
- 5. (Canceled)
- 6. (Currently Amended) An The electronic component according to claim 1, wherein the through hole comprises a plurality of holes arranged along the thickness direction of the substrate; and

wherein the holes formed adjacent each other in the thickness direction of the substrate are kept from overlapping each other as seen in the thickness direction of the substrate.

7. (Currently Amended) AnThe electronic component according to claim 1, further comprising a plurality of conductive films arranged with a gap therebetween extending in the thickness direction of the substrate; and

wherein the conductor electrically connects the conductive films to each other.

8. (Currently Amended) AnThe electronic component according to claim 7, wherein the through hole has a length D0 of

 $D0 \le 500 \mu m$

in each conductive film as seen in a minor axis direction.

- 9. (Currently Amended) AnThe electronic component according to claim 7, wherein the through hole is formed so as to have a major axis direction extending along a longitudinal direction of the conductive films.
- 10. (Currently Amended) AnThe electronic component according to claim 7, wherein the conductive film comprises a first electrode film, a first terminal electrode film, a second electrode film, and a second terminal electrode film;

wherein the first electrode film and first terminal electrode film are disposed at the same position as seen in the thickness direction of the substrate with a first insulating gap therebetween;

wherein the second electrode film and second terminal electrode film are disposed at the same position as seen in the thickness direction of the substrate with a second insulating gap therebetween;

wherein the second electrode film opposes the first electrode film and first terminal electrode film by way of the substrate;

wherein the second terminal electrode film opposes the first electrode film by way of the substrate;

wherein the conductor includes a first conductor and a second conductor;

wherein the first conductor electrically connects the first electrode film and the second terminal electrode film to each other; and

wherein the second conductor electrically connects the second electrode film and the first terminal electrode film to each other.

- 11. (Currently Amended) AnThe electronic component according to claim 10, wherein a group of the first electrode film and first terminal electrode film and a group of the second electrode film and second terminal electrode film are alternately disposed within the substrate with a gap in the thickness direction of the substrate.
- 12. (Currently Amended) AnThe electronic component according to claim 1, wherein the substrate comprises a piezoelectric material and functions as an actuator.